

BF 1608 Series

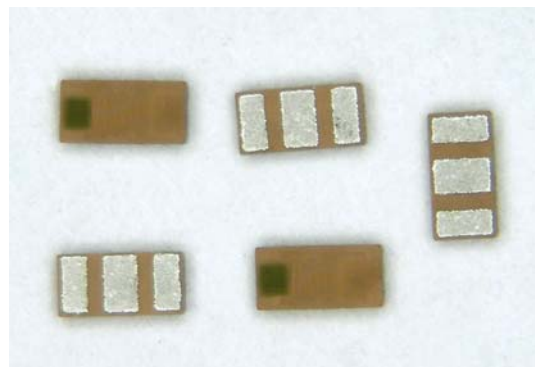
Multilayer Chip Band-Pass Filters

Features

- ❖ Ultra small SMD type with low loss at pass-band and high attenuation at stop-band.
- ❖ RoHS compliant.

Applications

- ❖ Mobile communication systems.



Specifications

Part Number	Freq.Range (MHz)	Insertion Loss @ BW(dB)	Return Loss @ BW(dB)	Frequency (MHz)	Attenuation (dB)
BF1608-L4R7NAC-P_	4400 ~ 5000	1.15 typ. / 1.5 max.	19 typ. / 10 min.	400 ~ 915	46 typ. / 35 min.
				925 ~ 2485	43 typ. / 30 min.
				2485 ~ 3600	31 typ. / 20 min.
				5850 ~ 6100	22 typ. / 7 min.
				6100 ~ 6980	21 typ. / 15 min.
				8800 ~ 10000	32 typ. / 25 min.
				13200 ~ 15000	39 typ. / 20 min.

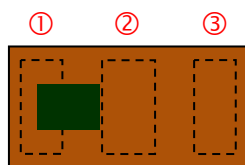
Q'ty/Reel (pcs) : 4,000
 Operating Temperature Range : -40 ~ +85 °C
 Storage Temperature Range : -40 ~ +85 °C
 Storage Period : 12 months max.
 Power Capacity : 3W max.

Part Number

BF 1608 - L 4R7 NAC-P □ /LF
 ① ② ③ ④ ⑤ ⑥ ⑦

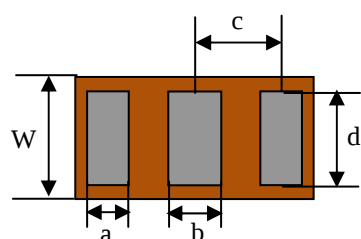
① Type	BF : Band-Pass Filter	② Dimensions (L × W)	1.6 × 0.8 mm
③ Material Code	L	④ Frequency Range	4R7=4700MHz
⑤ Specification Code	NAC-P	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	/LF=lead-free		

Terminal Configuration

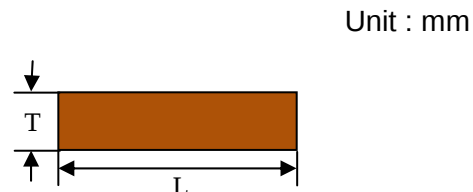


No.	Terminal Name	No.	Terminal Name
①	IN/OUT	③	IN/OUT
②	GND		

Dimensions and Recommended PC Board Pattern

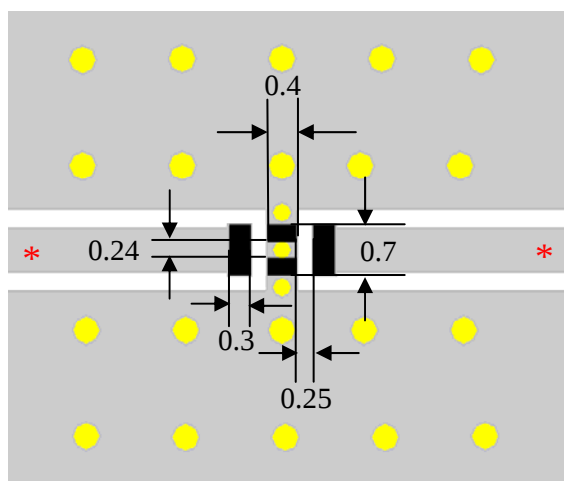


< Bottom View >



< Side View >

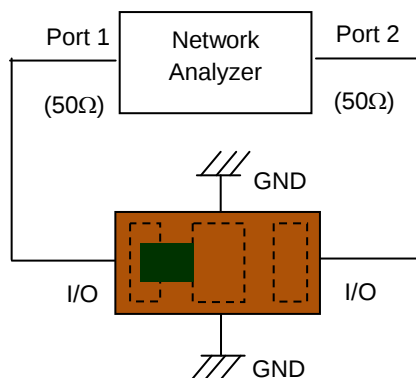
Mark	L	W	T	a	b	c	d
Dimensions	1.6 ± 0.1	0.8 ± 0.1	0.35 max.	0.3 ± 0.1	0.4 ± 0.1	0.6 ± 0.1	0.7 ± 0.1



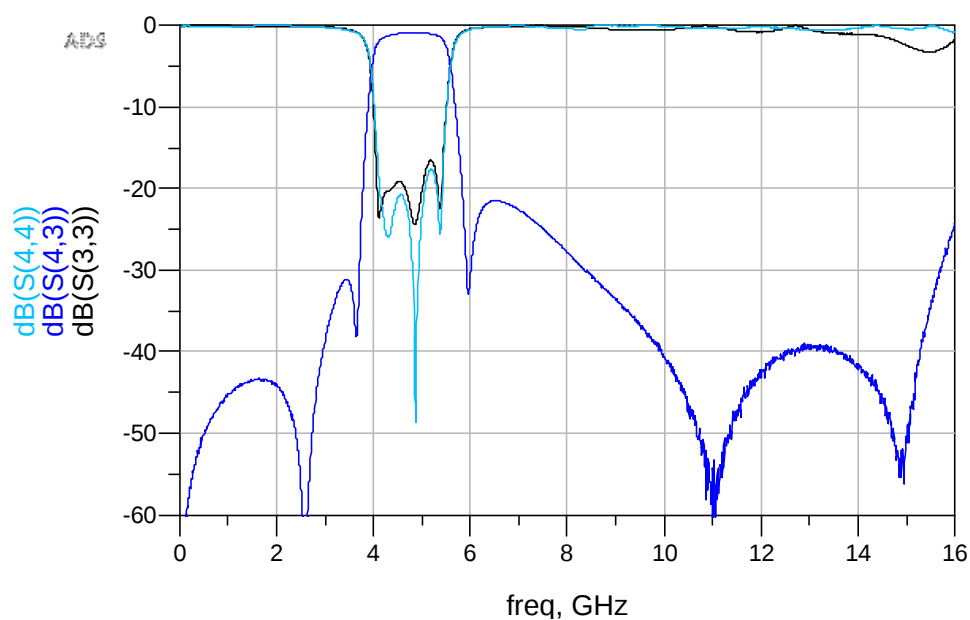
-  Solder Resist
-  Land
-  Through-hole (ϕ 0.35, 0.23)

* Line width should be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness.

Measuring Diagram



Electrical Characteristics (T=25°C)

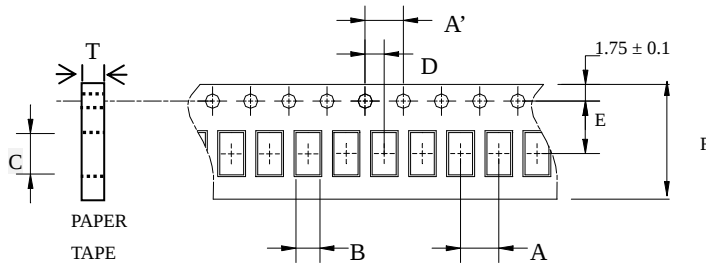


Notes

❖ The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

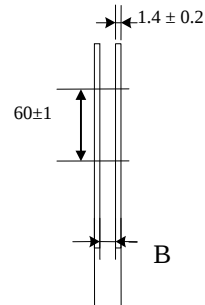
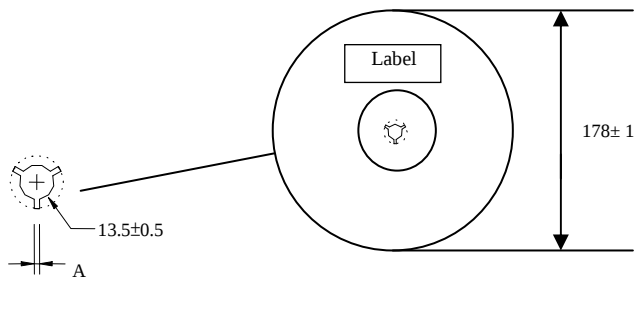
Taping Specifications

❖Tape Dimensions (Unit: mm) & Quantity



Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
1608	4.0± 0.1	4.0± 0.1	0.95± 0.1	1.80± 0.1	2.0± 0.1	3.5± 0.1	8.0± 0.1	0.60± 0.03	4,000pcs	Paper

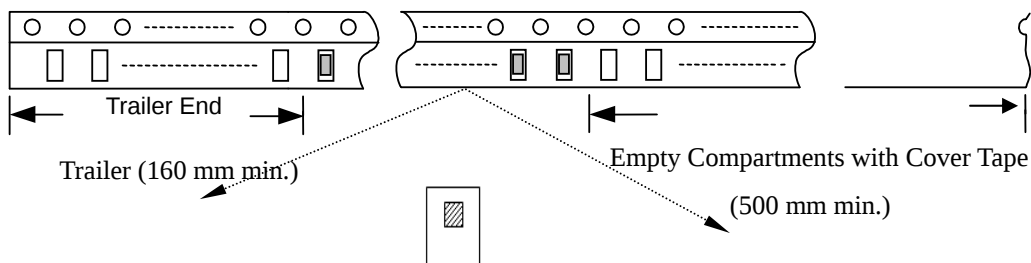
❖Reel Dimensions (Unit: mm)



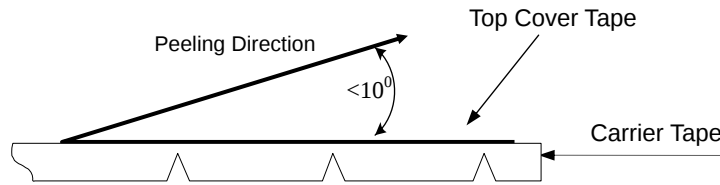
Label: Customer's Name,
ACX P/N, Q'ty, Date,
ACX Corp.

Type	A	B
1608	2.3±0.5	9.0±0.3

❖Leader and Trailer Tape



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

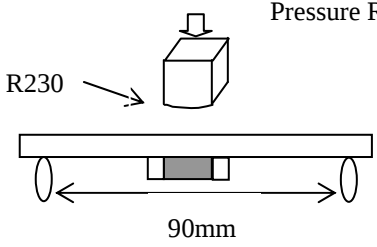
❖ **Storage Conditions**

- (1) Temperature: 5 ~35°C , relative humidity (RH): 45~75%.
- (2) Non-corrosive environment

Notes

- ❖ The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

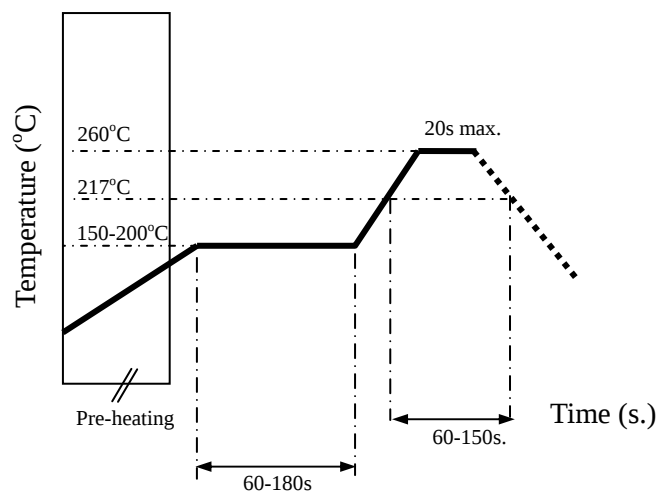
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	1. No apparent damage 2. More than 95% of the terminal electrode shall be covered with new solder	1. Preheat: $120 \pm 5^{\circ}\text{C}$ 2. Solder: $245 \pm 5^{\circ}\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	1. 10N minimum	1. Solder specimen onto test jig. 2. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	1. No apparent damage	1. Solder specimen onto test jig (FR4, 1.6mm) using the recommend soldering profile. 2. Apply a bending force of 2mm deflection 
Heat/Humidity Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: $85 \pm 2^{\circ}\text{C}$ 2. Humidity: 90% ~ 95% RH 3. Duration: 1000 ± 48hrs 4. Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	1. No apparent damage 2. Fulfill the electrical specification after test	1. One cycle/step 1 : $125 \pm 5^{\circ}\text{C}$ for 30 min step 2 : $-40 \pm 5^{\circ}\text{C}$ for 30 min 2. No of cycles : 100 3. Recovery: 1-2 hrs
Low Temperature Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: $-40 \pm 5^{\circ}\text{C}$ 2. Duration: 500 ± 24hrs 3. Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



Notes

❖ The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

Advanced Ceramic X Corp.

16 Tzu Chiang Road, Hsinchu Industrial District Hsinchu Hsien 303, Taiwan

TEL:886-3-5987008 FAX:886-3-5987001

E-mail: acx@acxc.com.tw

<http://www.acxc.com.tw>